



LMx35, LMx35A Precision Temperature Sensors

1 Features

- Directly Calibrated to the Kelvin Temperature Scale
- 1°C Initial Accuracy Available
- Operates from 400 μ A to 5 mA
- Less than 1- Ω Dynamic Impedance
- Easily Calibrated
- Wide Operating Temperature Range
- 200°C Overrange
- Low Cost

2 Applications

- Power Supplies
- Battery Management
- HVAC
- Appliances

3 Description

The LM135 series are precision, easily-calibrated, integrated circuit temperature sensors. Operating as a 2-terminal zener, the LM135 has a breakdown voltage directly proportional to absolute temperature at 10 mV/°K. With less than 1- Ω dynamic impedance, the device operates over a current range of 400 μ A to 5 mA with virtually no change in performance. When calibrated at 25°C, the LM135 has typically less than 1°C error over a 100°C temperature range. Unlike other sensors, the LM135 has a linear output.

Applications for the LM135 include almost any type of temperature sensing over a -55°C to 150°C temperature range. The low impedance and linear output make interfacing to readout or control circuitry are especially easy.

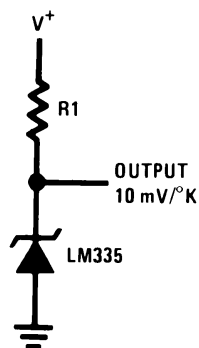
The LM135 operates over a -55°C to 150°C temperature range while the LM235 operates over a -40°C to 125°C temperature range. The LM335 operates from -40°C to 100°C. The LMx35 devices are available packaged in hermetic TO transistor packages while the LM335 is also available in plastic TO-92 packages.

Device Information⁽¹⁾

| PART NUMBER | PACKAGE | BODY SIZE (NOM) |
|-------------|-----------|---------------------|
| LM135 | TO-46 (3) | 4.699 mm x 4.699 mm |
| LM135A | | |
| LM235 | TO-92 (3) | 4.30 mm x 4.30 mm |
| LM235A | | |
| LM335 | SOIC (8) | 4.90 mm x 3.91 mm |
| LM335A | | |

(1) For all available packages, see the orderable addendum at the end of the datasheet.

Basic Temperature Sensor Simplified Schematic



Calibrated Sensor

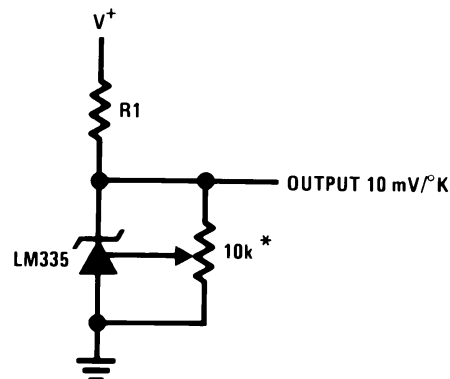


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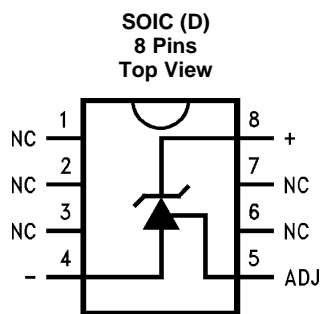
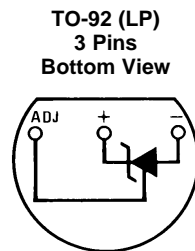
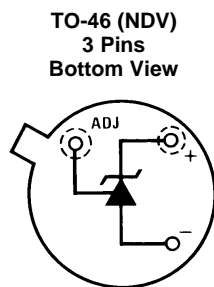
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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

| Changes from Revision D (March 2013) to Revision E | Page |
|---|-------------|
| <ul style="list-style-type: none"> Added <i>Pin Configuration and Functions</i> section, <i>Feature Description</i> section, <i>Device Functional Modes</i>, <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section | 1 |
| Changes from Revision C (November 2012) to Revision D | Page |
| <ul style="list-style-type: none"> Changed layout of National Data Sheet to TI format | 18 |

5 Pin Configuration and Functions



Pin Functions

| PIN | | | | I/O | DESCRIPTION |
|------|-------|-------|-----|-----|------------------------|
| NAME | TO-46 | TO-92 | SO8 | | |
| N.C. | — | — | 1 | — | No Connection |
| | — | — | 2 | | |
| | — | — | 3 | | |
| - | — | — | 4 | O | Negative output |
| ADJ | — | — | 5 | I | Calibration adjust pin |
| N.C. | — | — | 6 | — | No Connection |
| | — | — | 7 | | |
| + | — | — | 8 | I | Positive input |

6 Specifications

6.1 Absolute Maximum Ratings

 over operating free-air temperature range (unless otherwise noted)⁽¹⁾⁽²⁾⁽³⁾⁽⁴⁾

| | | MIN | MAX | UNIT |
|--|--------------------|-----|-----|------|
| Reverse Current | | | 15 | mA |
| Forward Current | | | 10 | mA |
| Storage temperature, T _{stg} | 8-Pin SOIC Package | –65 | 150 | °C |
| | TO / TO-92 Package | –60 | 150 | °C |

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) Refer to RETS135H for military specifications.
- (3) If Military/Aerospace specified devices are required, please contact the TI Sales Office/Distributors for availability and specifications.
- (4) Soldering process must comply with the Reflow Temperature Profile specifications. Refer to <http://www.ti.com/packaging>.

6.2 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

| | | | MIN | NOM | MAX | UNIT |
|-----------------------|---------------|--|-----|-----|-----|------|
| Specified Temperature | LM135, LM135A | Continuous ($T_{MIN} \leq T_A \leq T_{MAX}$) | –55 | | 150 | °C |
| | | Intermittent ⁽¹⁾ | 150 | | 200 | |
| | LM235, LM235A | Continuous ($T_{MIN} \leq T_A \leq T_{MAX}$) | –40 | | 125 | °C |
| | | Intermittent ⁽¹⁾ | 125 | | 150 | |
| | LM335, LM335A | Continuous ($T_{MIN} \leq T_A \leq T_{MAX}$) | –40 | | 100 | °C |
| | | Intermittent ⁽¹⁾ | 100 | | 125 | |
| Forward Current | | | 0.4 | 1 | 5 | mA |

- (1) Continuous operation at these temperatures for 5,000 hours for LP package may decrease life expectancy of the device.

6.3 Thermal Information

| THERMAL METRIC ⁽¹⁾ | | LM335 / LM335A | LM235 / LM235A | LM135 / LM135A | UNIT |
|-------------------------------|--|-------------------|-------------------|-------------------|------|
| | | SOIC (D) | TO-92 (LP) | TO-46 (NDV) | |
| | | 8 PINS | 3 PINS | 3 PINS | |
| R _{θJA} | Junction-to-ambient thermal resistance | 165 | 202 | 400 | °C/W |
| R _{θJC} | Junction-to-case thermal resistance | — | 170 | — | |

- (1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](http://www.ti.com/lit/an/SPRA953).

6.4 Temperature Accuracy: LM135/LM235, LM135A/LM235A⁽¹⁾

| PARAMETER | | TEST CONDITIONS | LM135A/LM235A | | | LM135/LM235 | | | UNIT |
|--------------------------------|------------------------------|--|---------------|------|------|-------------|------|------|------|
| | | | MIN | TYP | MAX | MIN | TYP | MAX | |
| Operating Output Voltage | | T _C = 25°C, I _R = 1 mA | 2.97 | 2.98 | 2.99 | 2.95 | 2.98 | 3.01 | V |
| Uncalibrated Temperature Error | | T _C = 25°C, I _R = 1 mA | | 0.5 | 1 | | 1 | 3 | °C |
| Uncalibrated Temperature Error | | T _{MIN} ≤ T _C ≤ T _{MAX} , I _R = 1 mA | | 1.3 | 2.7 | | 2 | 5 | °C |
| Temperature Error with 25°C | | T _{MIN} ≤ T _C ≤ T _{MAX} , I _R = 1 mA | | 0.3 | 1 | | 0.5 | 1.5 | °C |
| Calibration | Calibrated Error at Extended | T _C = T _{MAX} (Intermittent) | | 2 | | | 2 | | °C |
| Temperature | Non-Linearity | I _R = 1 mA | | 0.3 | 0.5 | | 0.3 | 1 | °C |

- (1) Accuracy measurements are made in a well-stirred oil bath. For other conditions, self heating must be considered.

6.5 Temperature Accuracy: LM335, LM335A⁽¹⁾

| PARAMETER | | TEST CONDITIONS | LM335A | | | LM335 | | | UNIT |
|---|------------------------------|---|--------|------|------|-------|------|------|------------------|
| | | | MIN | TYP | MAX | MIN | TYP | MAX | |
| Operating Output Voltage | | $T_C = 25^\circ\text{C}$, $I_R = 1\text{ mA}$ | 2.95 | 2.98 | 3.01 | 2.92 | 2.98 | 3.04 | V |
| Uncalibrated Temperature Error | | $T_C = 25^\circ\text{C}$, $I_R = 1\text{ mA}$ | | 1 | 3 | | 2 | 6 | $^\circ\text{C}$ |
| Uncalibrated Temperature Error | | $T_{\text{MIN}} \leq T_C \leq T_{\text{MAX}}$, $I_R = 1\text{ mA}$ | | 2 | 5 | | 4 | 9 | $^\circ\text{C}$ |
| Temperature Error with 25°C | | $T_{\text{MIN}} \leq T_C \leq T_{\text{MAX}}$, $I_R = 1\text{ mA}$ | | 0.5 | 1 | | 1 | 2 | $^\circ\text{C}$ |
| Calibration | Calibrated Error at Extended | $T_C = T_{\text{MAX}}$ (Intermittent) | | 2 | | | 2 | | $^\circ\text{C}$ |
| Temperature | Non-Linearity | $I_R = 1\text{ mA}$ | | 0.3 | 1.5 | | 0.3 | 1.5 | $^\circ\text{C}$ |

(1) Accuracy measurements are made in a well-stirred oil bath. For other conditions, self heating must be considered.

6.6 Electrical Characteristics

See ⁽¹⁾.

| PARAMETER | TEST CONDITIONS | LM135/LM235/LM135A/LM235A | | | LM335/LM335A | | | UNIT |
|--|--|---------------------------|-----|-----|--------------|-----|-----|----------------------------|
| | | MIN | TYP | MAX | MIN | TYP | MAX | |
| Operating Output Voltage Change with Current | $400\text{ }\mu\text{A} \leq I_R \leq 5\text{ mA}$, At Constant Temperature | | 2.5 | 10 | | 3 | 14 | mV |
| Dynamic Impedance | $I_R = 1\text{ mA}$ | | 0.5 | | | 0.6 | | Ω |
| Output Voltage Temperature Coefficient | | | 10 | | | 10 | | mV/ $^\circ\text{C}$ |
| Time Constant | Still Air | | 80 | | | 80 | | sec |
| | 100 ft/Min Air | | 10 | | | 10 | | sec |
| | Stirred Oil | | 1 | | | 1 | | sec |
| Time Stability | $T_C = 125^\circ\text{C}$ | | 0.2 | | | 0.2 | | $^\circ\text{C}/\text{hr}$ |

(1) Accuracy measurements are made in a well-stirred oil bath. For other conditions, self heating must be considered.

6.7 Typical Characteristics

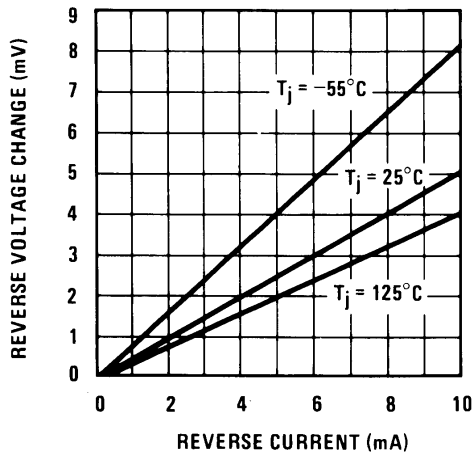


Figure 1. Reverse Voltage Change

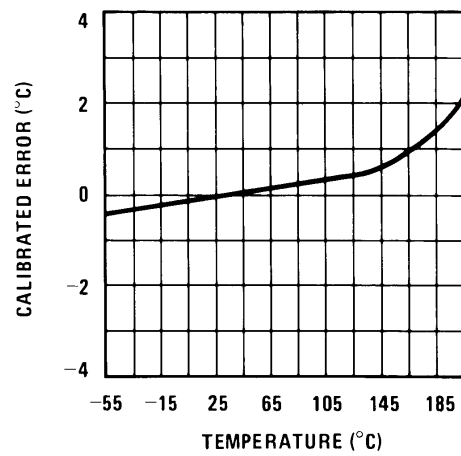


Figure 2. Calibrated Error

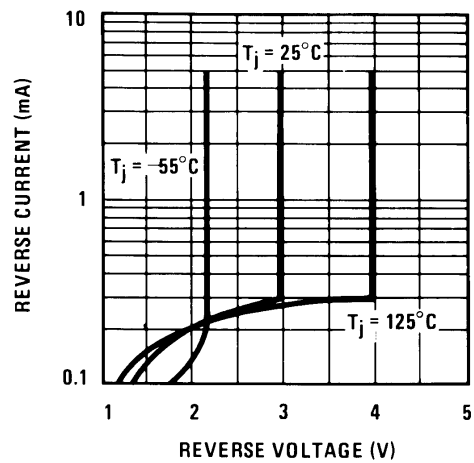


Figure 3. Reverse Characteristics

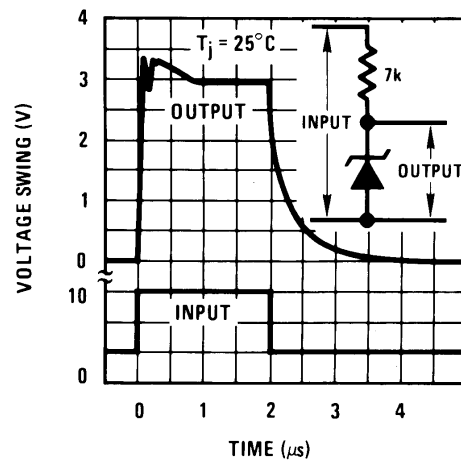


Figure 4. Response Time

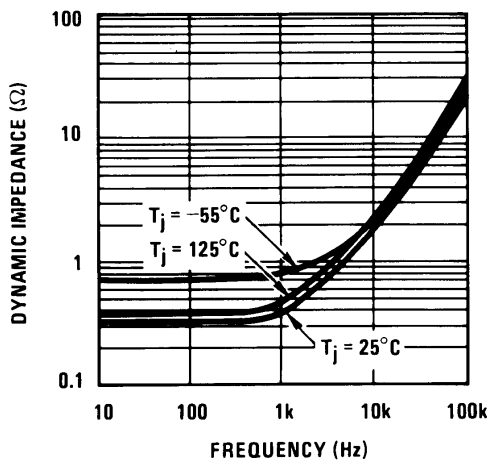


Figure 5. Dynamic Impedance

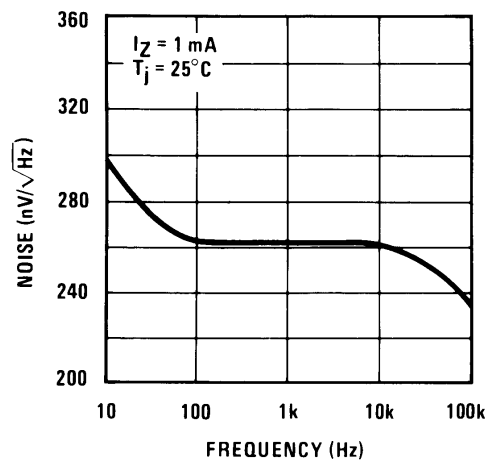


Figure 6. Noise Voltage

Typical Characteristics (continued)

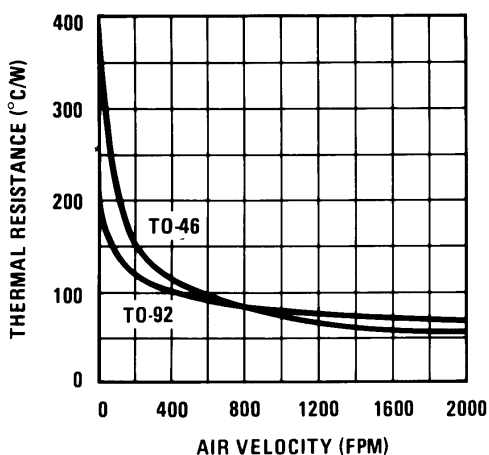


Figure 7. Thermal Resistance Junction To Air

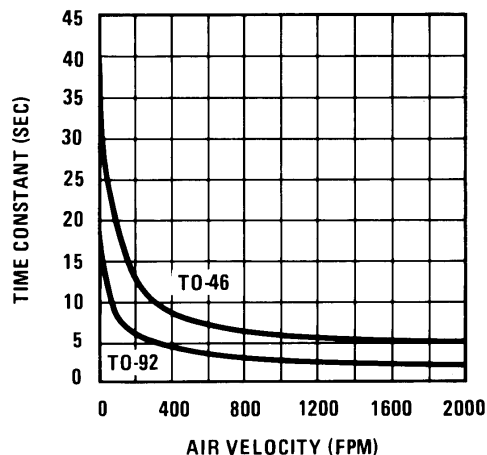


Figure 8. Thermal Time Constant

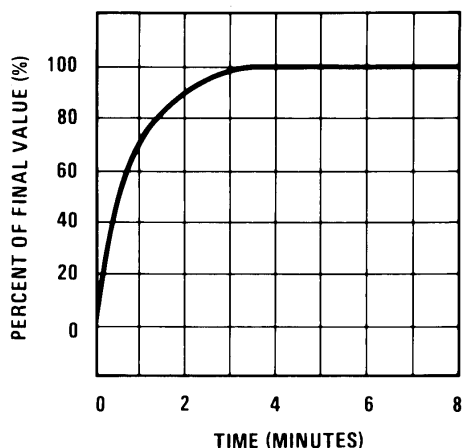


Figure 9. Thermal Response In Still Air

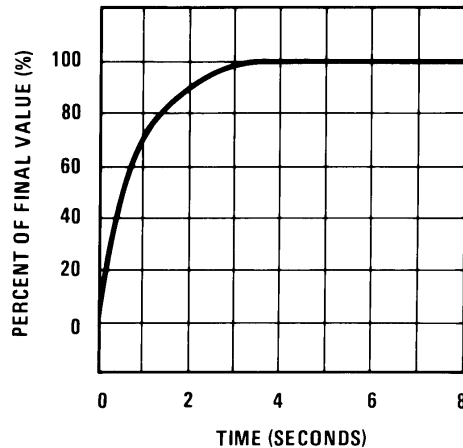


Figure 10. Thermal Response In Stirred Oil Bath

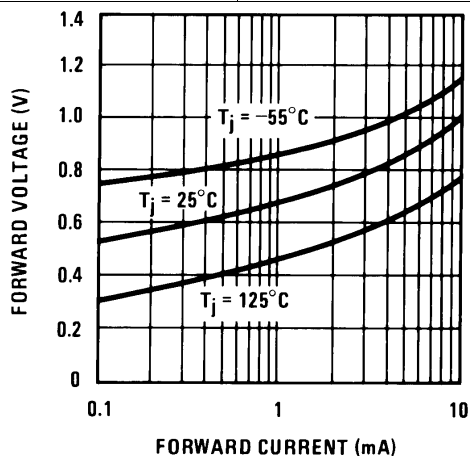


Figure 11. Forward Characteristics

7 Detailed Description

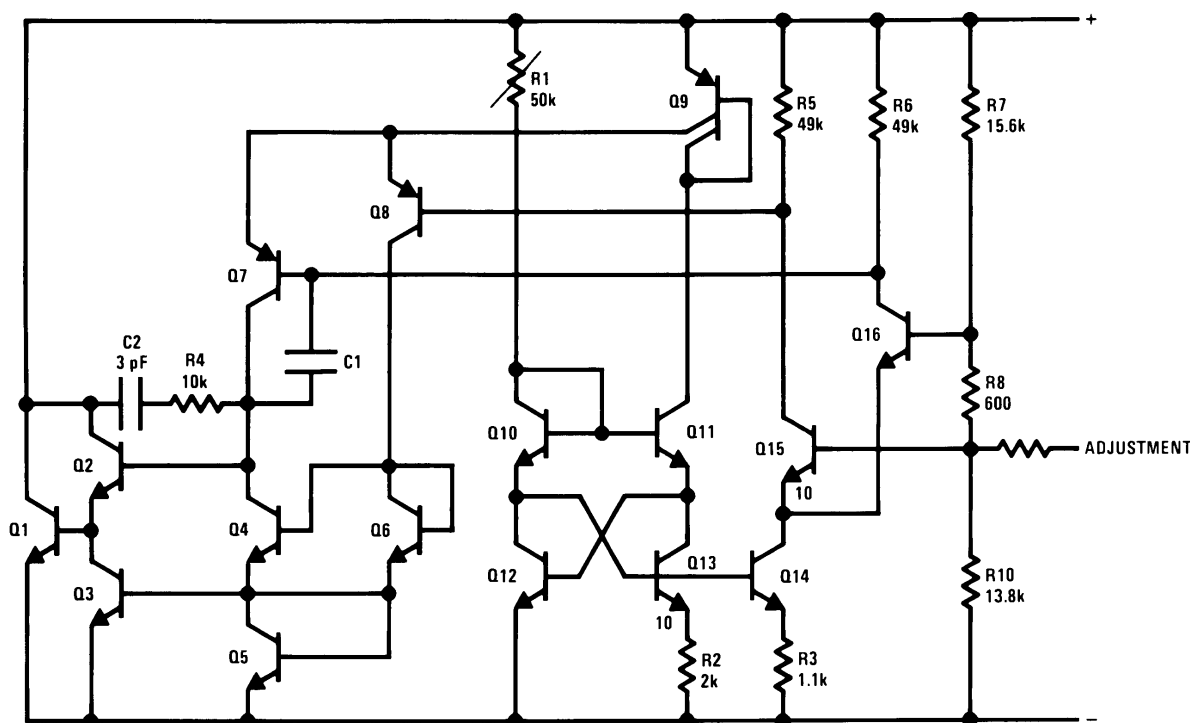
7.1 Overview

Applications for the LM135 include almost any type of temperature sensing over a -55°C to 150°C temperature range. The low impedance and linear output make interfacing to readout or control circuitry especially easy.

The LM135 operates over a -55°C to 150°C temperature range while the LM235 operates over a -40°C to 125°C temperature range. The LM335 operates from -40°C to 100°C .

Operating as a 2-terminal zener, the LM135 has a breakdown voltage directly proportional to absolute temperature at $10\text{ mV}/^{\circ}\text{K}$. With less than $1\text{-}\Omega$ dynamic impedance, the device operates over a current range of $400\text{ }\mu\text{A}$ to 5 mA with virtually no change in performance. When calibrated at 25°C , the LM135 has typically less than 1°C error over a 100°C temperature range. Unlike other sensors, the LM135 has a linear output.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Temperature Calibration Using ADJ Pin

Included on the LM135 chip is an easy method of calibrating the device for higher accuracies. A pot connected across the LM135 with the arm tied to the adjustment terminal (as shown in [Figure 12](#)) allows a 1-point calibration of the sensor that corrects for inaccuracy over the full temperature range.

This single point calibration works because the output of the LM135 is proportional to absolute temperature with the extrapolated output of sensor going to 0-V output at 0 K (-273.15°C). Errors in output voltage versus temperature are only slope (or scale factor) errors so a slope calibration at one temperature corrects at all temperatures.

The output of the device (calibrated or uncalibrated) can be expressed as:

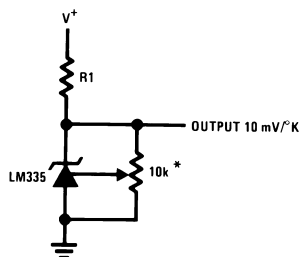
$$V_{\text{OUT}_T} = V_{\text{OUT}_{T_0}} \times \frac{T}{T_0}$$

where

Feature Description (continued)

- T is the unknown temperature in degrees Kelvin
- T_o is a reference temperature in degrees Kelvin (1)

By calibrating the output to read correctly at one temperature the output at all temperatures is correct. Nominally the output is calibrated at 10 mV/K.



Calibrate for 2.982V at 25°C

Figure 12. Calibrated Sensor

7.4 Device Functional Modes

The LM135 has two functional modes calibrated and uncalibrated. For optimum accuracy, a one point calibration is recommended. For more information on calibration, see [Temperature Calibration Using ADJ Pin](#).

8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

To insure good sensing accuracy, several precautions must be taken. Like any temperature-sensing device, self-heating can reduce accuracy. The LM135 should be operated at the lowest current suitable for the application. Sufficient current, of course, must be available to drive both the sensor and the calibration pot at the maximum operating temperature as well as any external loads.

If the sensor is used in an ambient where the thermal resistance is constant, self-heating errors can be calibrated out. This is possible if the device is run with a temperature-stable current. Heating will then be proportional to zener voltage and therefore temperature. This makes the self-heating error proportional to absolute temperature the same as scale factor errors.

8.2 Typical Application

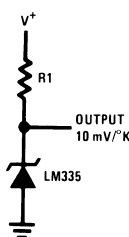


Figure 13. Basic Temperature Sensor

8.2.1 Design Requirements

Table 1. Design Parameters

| PARAMETER | EXAMPLE VALUE |
|--------------------------------|---------------|
| Accuracy at 25°C | ±1°C |
| Accuracy from –55 °C to 150 °C | ±2.7°C |
| Forward Current | 1 mA |
| Temperature Slope | 10m V/K |

8.2.2 Detailed Design Procedure

For optimum accuracy, R1 is picked such that 1 mA flows through the sensor. Additional error can be introduced by varying load currents or varying supply voltage. The influence of these currents on the minimum and maximum reverse current flowing through the LM135 should be calculated and be maintained in the range of 0.4 mA to 5 mA. Minimizing the current variation through the LM135 will provide for the best accuracy. The Operating Output Voltage Change with Current specification can be used to calculate the additional error which could be up to 1 K maximum from the LM135A, for example.

8.2.3 Application Curve

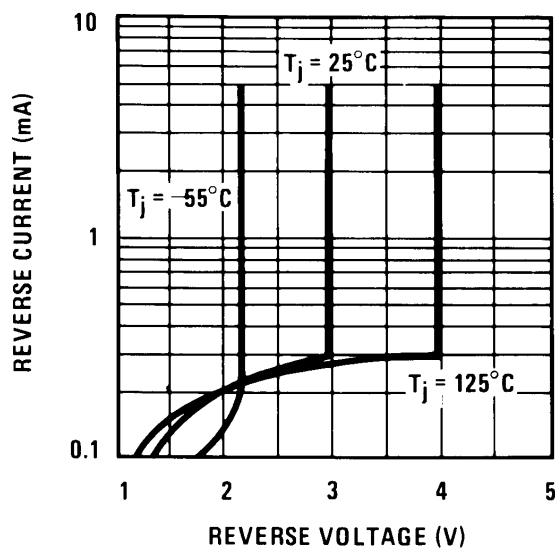


Figure 14. Reverse Characteristics

8.3 System Examples

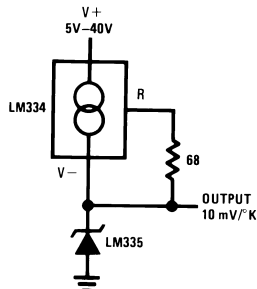


Figure 15. Wide Operating Supply

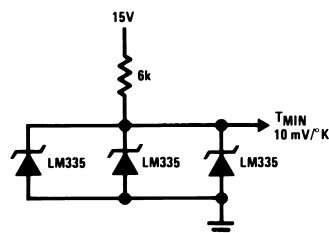


Figure 16. Minimum Temperature Sensing

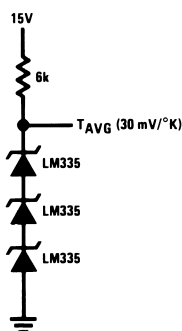


Figure 17. Average Temperature Sensing

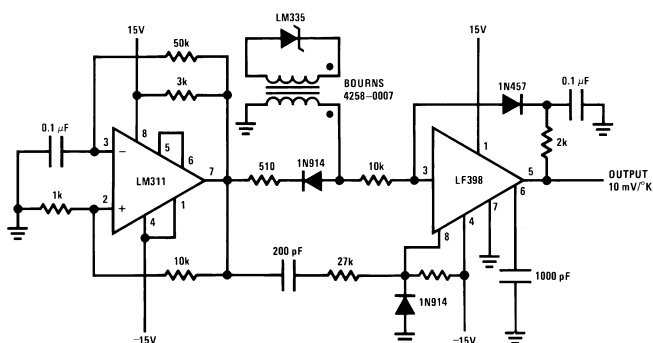


Figure 18. Isolated Temperature Sensor

Wire length for 1°C error due to wire drop

System Examples (continued)

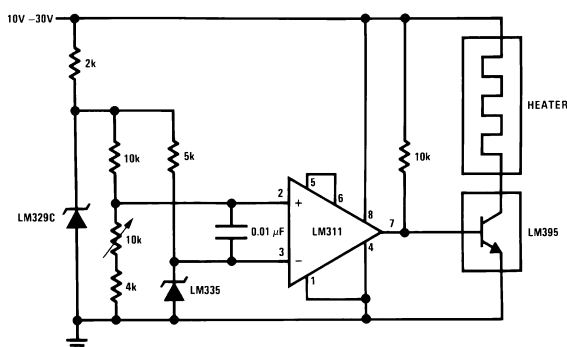


Figure 19. Simple Temperature Controller

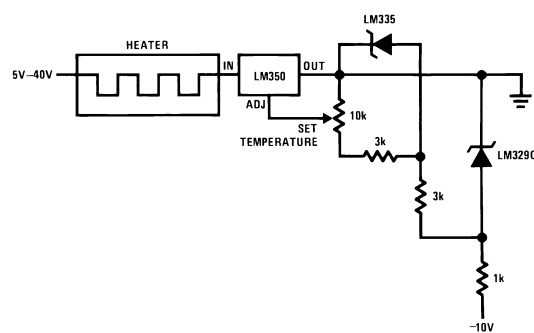
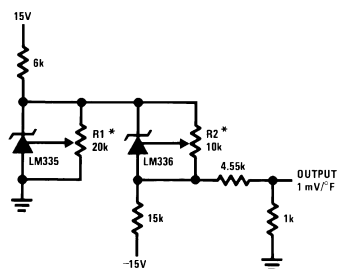


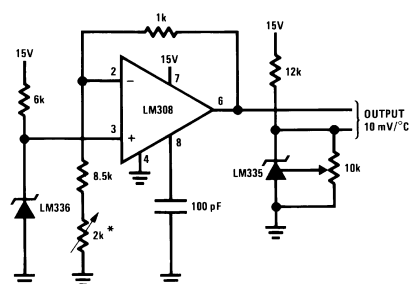
Figure 20. Simple Temperature Control



Adjust R2 for 2.554V across LM336.

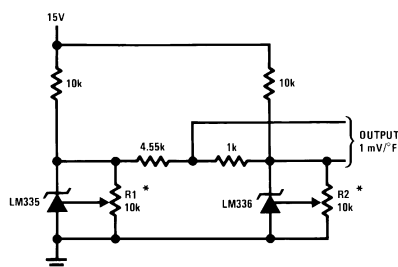
Adjust R1 for correct output.

Figure 21. Ground Referred Fahrenheit Thermometer



Adjust for 2.7315V at output of LM308

Figure 22. Centigrade Thermometer

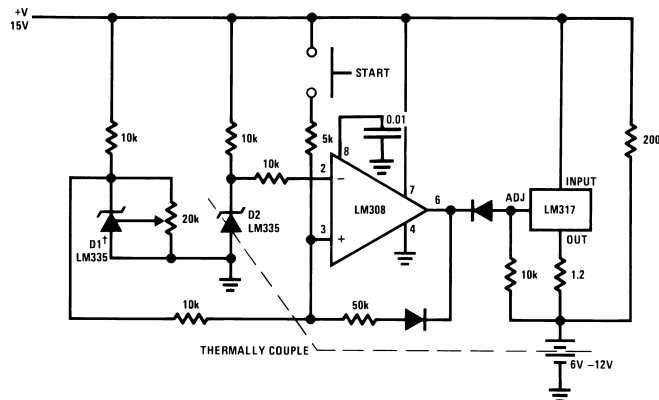


To calibrate adjust R2 for 2.554V across LM336.

Adjust R1 for correct output.

Figure 23. Fahrenheit Thermometer





Adjust D1 to 50 mV greater V_Z than D2.
Charge terminates on 5°C temperature rise.
Couple D2 to battery.

Figure 29. Fast Charger For Nickel-Cadmium Batteries

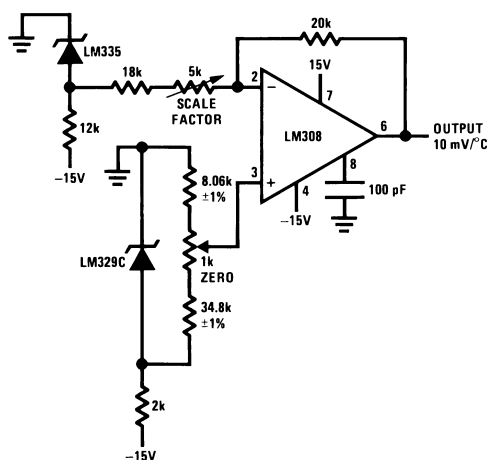
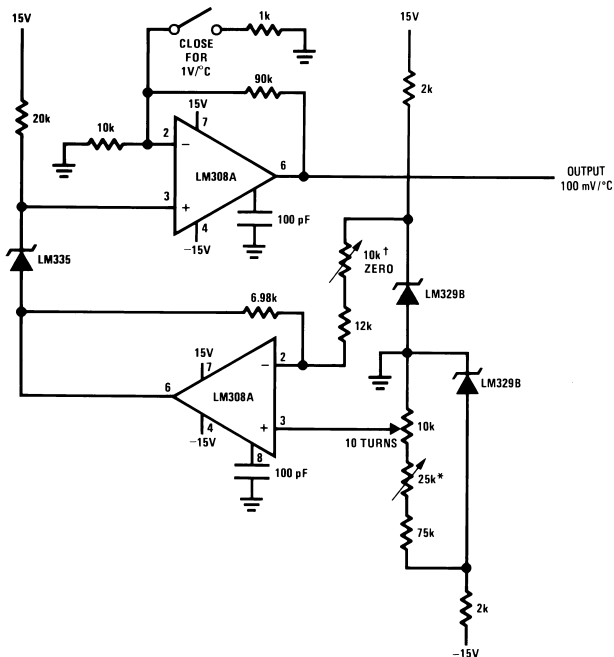


Figure 31. Ground Referred Centigrade Thermometer

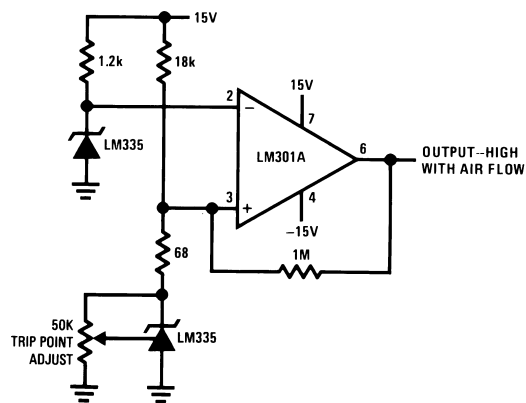


Adjust for zero with sensor at 0°C and 10T pot set at 0°C

Adjust for zero output with 10T pot set at 100°C and sensor at 100°C

Output reads difference between temperature and dial setting of 10T pot

Figure 30. Variable Offset Thermometer



*Self heating is used to detect air flow

Figure 32. Air Flow Detector

9 Power Supply Recommendations

Ensure the LM335 is biased properly with a current ranging 0.4 mA to 5 mA.

10 Layout

10.1 Layout Guidelines

The LM135 is applied easily in the same way as other integrated-circuit temperature sensors. Glue or cement the device to a surface and the temperature should be within about 0.01°C of the surface temperature.

Efficient temperature transfer assumes that the ambient air temperature is almost the same as the surface temperature where the LM135 leads are attached. If there is a great difference between the air temperature and the surface temperature, the actual temperature of the LM135 die would be at an intermediate temperature between the two temperatures. For example, the TO-92 plastic package, where the copper leads are the principal thermal path to carry heat into the device, can be greatly affected by airflow. The temperature sensed by the TO92 package could greatly depend on velocity of the airflow as well.

To lessen the affect of airflow, ensure that the wiring to the LM135 (leads and wires connected to the leads) is held at the same temperature as the surface temperature that is targeted for measurement. To insure that the temperature of the LM135 die is not affected by the air temperature, mechanically connect the LM135 leads with a bead of epoxy to the surface being measured. If air temperature is targeted for measurement ensure that the PCB surface temperature is close to the air temperature. Keep the LM135 away from offending PCB heat sources such as power regulators. One method commonly used for thermal isolation is to route a thermal well as shown in [Figure 33](#) with the smallest possible geometry traces connecting back to rest of the PCB.

10.2 Layout Example

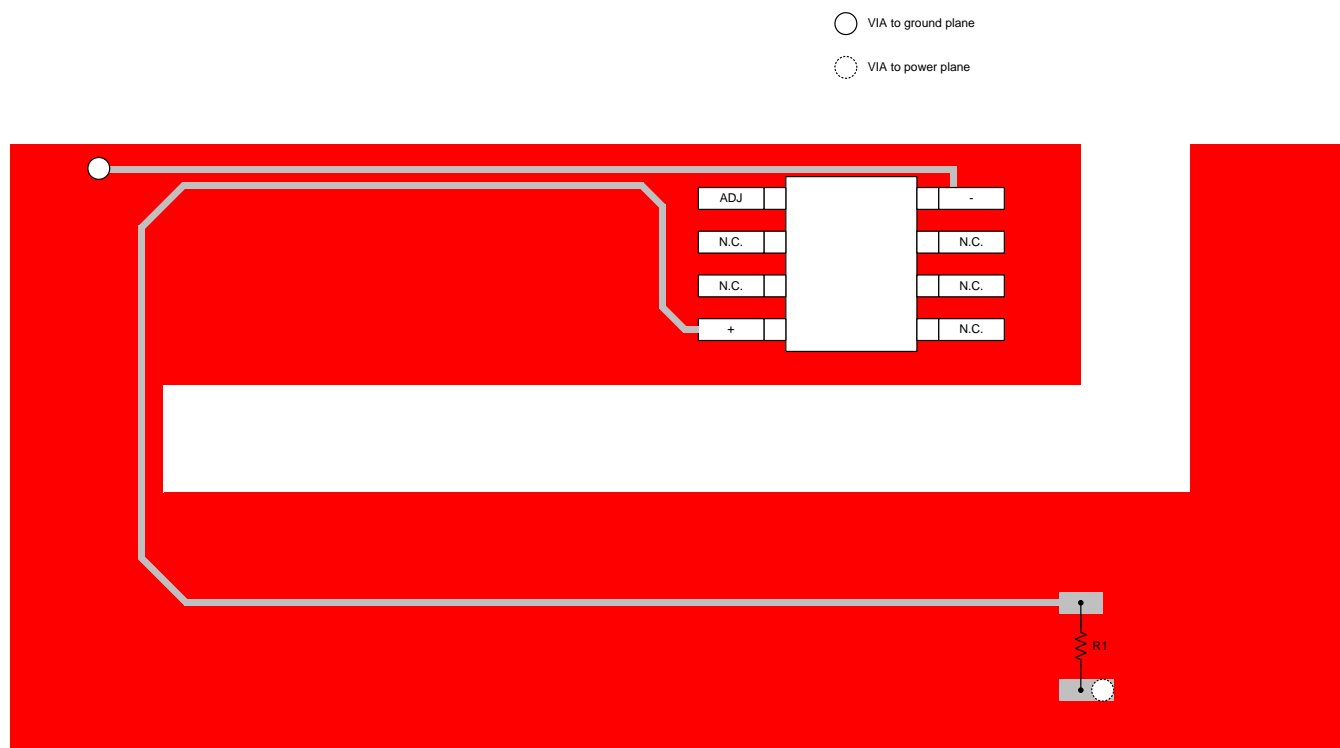


Figure 33. Layout Example

10.3 Waterproofing Sensors

Meltable inner-core, heat-shrinkable tubing, such as manufactured by Raychem, can be used to make low-cost waterproof sensors. The LM335 is inserted into the tubing about 0.5 inches from the end and the tubing heated above the melting point of the core. The unfilled 0.5-inch end melts and provides a seal over the device.

10.4 Mounting the Sensor at the End of a Cable

The main error due to a long wire is caused by the voltage drop across that wire caused by the reverse current biasing the LM135 on. Table 2 shows the wire AWG and the length of wire that would cause 1°C error.

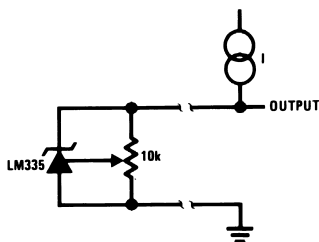


Figure 34. Cable Connected Temperature Sensor

Table 2. Wire Length for 1°C Error Due to Wire Drop

| AWG | $I_R = 1 \text{ mA}$ | $I_R = 0.5 \text{ mA}^{(1)}$ |
|-----|----------------------|------------------------------|
| | FEET | FEET |
| 14 | 4000 | 8000 |
| 16 | 2500 | 5000 |
| 18 | 1600 | 3200 |
| 20 | 1000 | 2000 |
| 22 | 625 | 1250 |
| 24 | 400 | 800 |

(1) For $I_R = 0.5 \text{ mA}$, the trim pot must be deleted.

11 Device and Documentation Support

11.1 Device Support

11.1.1 Device Nomenclature

Operating Output Voltage: The voltage appearing across the positive and negative terminals of the device at specified conditions of operating temperature and current.

Uncalibrated Temperature Error: The error between the operating output voltage at 10 mV/°K and case temperature at specified conditions of current and case temperature.

Calibrated Temperature Error: The error between operating output voltage and case temperature at 10 mV/°K over a temperature range at a specified operating current with the 25°C error adjusted to zero.

11.2 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 3. Related Links

| PARTS | PRODUCT FOLDER | SAMPLE & BUY | TECHNICAL DOCUMENTS | TOOLS & SOFTWARE | SUPPORT & COMMUNITY |
|--------|----------------------------|----------------------------|----------------------------|----------------------------|----------------------------|
| LM135 | Click here | Click here | Click here | Click here | Click here |
| LM135A | Click here | Click here | Click here | Click here | Click here |
| LM235 | Click here | Click here | Click here | Click here | Click here |
| LM235A | Click here | Click here | Click here | Click here | Click here |
| LM335 | Click here | Click here | Click here | Click here | Click here |
| LM335A | Click here | Click here | Click here | Click here | Click here |

11.3 Trademarks

All trademarks are the property of their respective owners.

11.4 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

11.5 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| LM135AH | ACTIVE | TO | NDV | 3 | 500 | TBD | Call TI | Call TI | -55 to 150 | (LM135AH, LM135AH) | Samples |
| LM135AH/NOPB | ACTIVE | TO | NDV | 3 | 500 | Green (RoHS & no Sb/Br) | Call TI | Level-1-NA-UNLIM | -55 to 150 | (LM135AH, LM135AH) | Samples |
| LM135H | ACTIVE | TO | NDV | 3 | 500 | TBD | Call TI | Call TI | -55 to 150 | (LM135H, LM135H) | Samples |
| LM135H/NOPB | ACTIVE | TO | NDV | 3 | 500 | Green (RoHS & no Sb/Br) | Call TI | Level-1-NA-UNLIM | -55 to 150 | (LM135H, LM135H) | Samples |
| LM235AH | ACTIVE | TO | NDV | 3 | 500 | TBD | Call TI | Call TI | -40 to 125 | (LM235AH, LM235AH) | Samples |
| LM235AH/NOPB | ACTIVE | TO | NDV | 3 | 500 | Green (RoHS & no Sb/Br) | Call TI | Level-1-NA-UNLIM | -40 to 125 | (LM235AH, LM235AH) | Samples |
| LM235H | ACTIVE | TO | NDV | 3 | 500 | TBD | Call TI | Call TI | -40 to 125 | (LM235H, LM235H) | Samples |
| LM235H/NOPB | ACTIVE | TO | NDV | 3 | 500 | Green (RoHS & no Sb/Br) | Call TI | Level-1-NA-UNLIM | -40 to 125 | (LM235H, LM235H) | Samples |
| LM335A MWC | ACTIVE | WAFERSALE | YS | 0 | 1 | TBD | Call TI | Call TI | -40 to 85 | | Samples |
| LM335AH/NOPB | ACTIVE | TO | NDV | 3 | 1000 | Green (RoHS & no Sb/Br) | Call TI | Level-1-NA-UNLIM | -40 to 100 | (LM335AH, LM335AH) | Samples |
| LM335AM | NRND | SOIC | D | 8 | 95 | TBD | Call TI | Call TI | -40 to 100 | LM335 AM | |
| LM335AM/NOPB | ACTIVE | SOIC | D | 8 | 95 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -40 to 100 | LM335 AM | Samples |
| LM335AMX | NRND | SOIC | D | 8 | 2500 | TBD | Call TI | Call TI | -40 to 100 | LM335 AM | |
| LM335AMX/NOPB | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -40 to 100 | LM335 AM | Samples |
| LM335AZ/NOPB | ACTIVE | TO-92 | LP | 3 | 1800 | Green (RoHS & no Sb/Br) | CU SN | N / A for Pkg Type | -40 to 100 | LM335 AZ | Samples |
| LM335H | ACTIVE | TO | NDV | 3 | 1000 | TBD | Call TI | Call TI | -40 to 100 | (LM335H, LM335H) | Samples |
| LM335H/NOPB | ACTIVE | TO | NDV | 3 | 1000 | Green (RoHS & no Sb/Br) | Call TI | Level-1-NA-UNLIM | -40 to 100 | (LM335H, LM335H) | Samples |
| LM335M | NRND | SOIC | D | 8 | 95 | TBD | Call TI | Call TI | -40 to 100 | LM335 M | |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| LM335M/NOPB | ACTIVE | SOIC | D | 8 | 95 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -40 to 100 | LM335 M | Samples |
| LM335MX/NOPB | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -40 to 100 | LM335 M | Samples |
| LM335Z/LFT7 | ACTIVE | TO-92 | LP | 3 | 2000 | Green (RoHS & no Sb/Br) | CU SN | N / A for Pkg Type | | LM335 Z | Samples |
| LM335Z/NOPB | ACTIVE | TO-92 | LP | 3 | 1800 | Green (RoHS & no Sb/Br) | CU SN | N / A for Pkg Type | -40 to 100 | LM335 Z | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| LM335AMX | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.5 | 5.4 | 2.0 | 8.0 | 12.0 | Q1 |
| LM335AMX/NOPB | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.5 | 5.4 | 2.0 | 8.0 | 12.0 | Q1 |
| LM335MX/NOPB | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.5 | 5.4 | 2.0 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| LM335AMX | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 35.0 |
| LM335AMX/NOPB | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 35.0 |
| LM335MX/NOPB | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 35.0 |



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

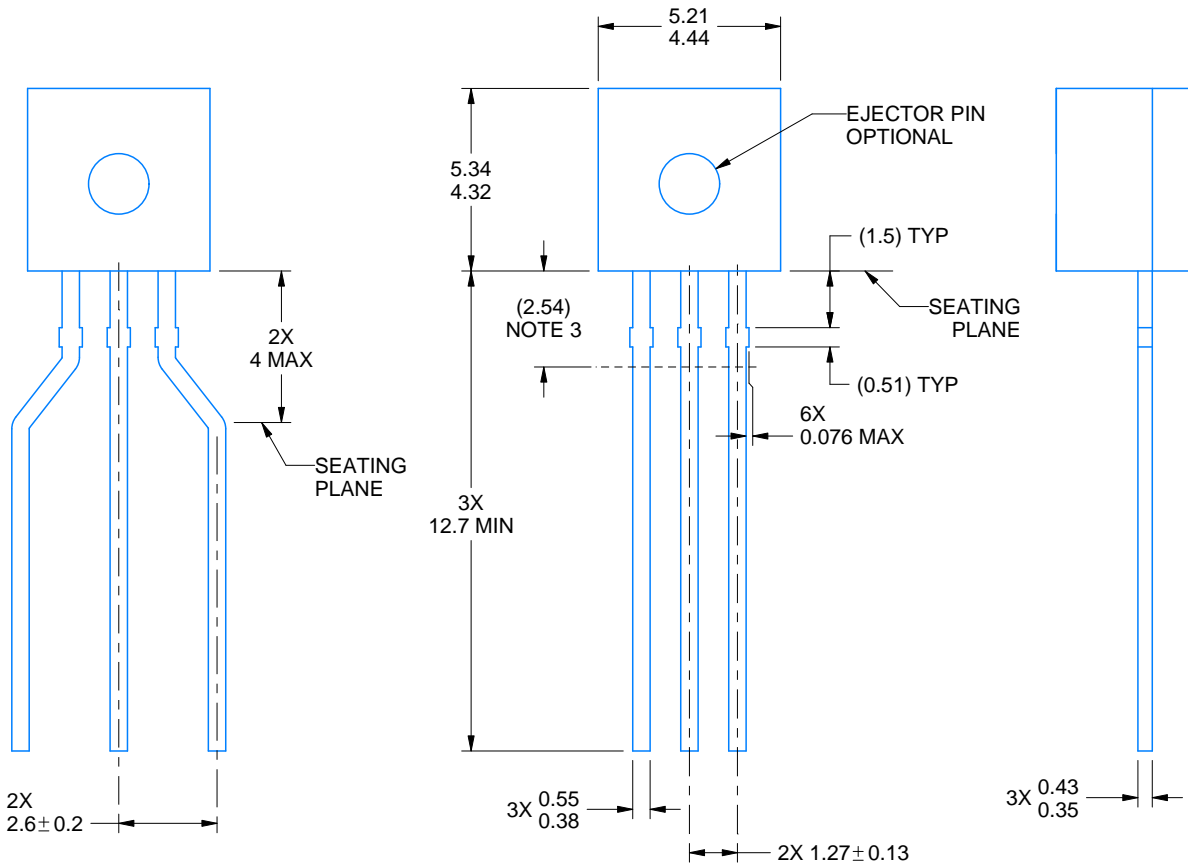
LP0003A



PACKAGE OUTLINE

TO-92 - 5.34 mm max height

TO-92



4215214/B 04/2017

NOTES:

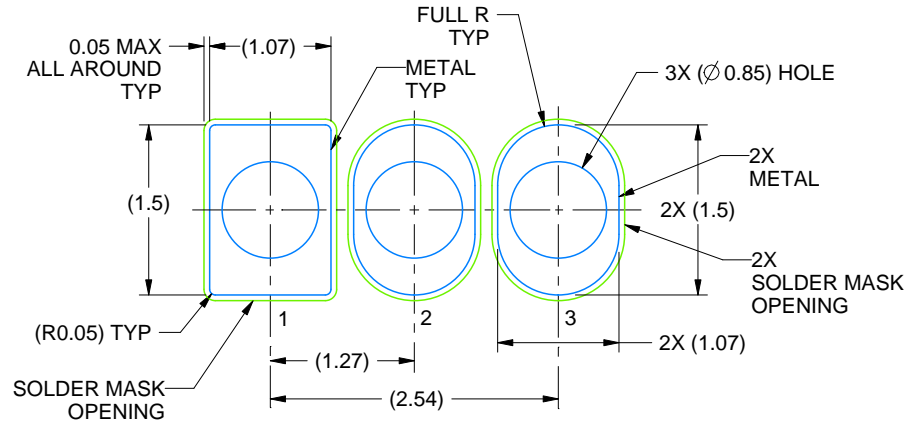
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Lead dimensions are not controlled within this area.
4. Reference JEDEC TO-226, variation AA.
5. Shipping method:
 - a. Straight lead option available in bulk pack only.
 - b. Formed lead option available in tape and reel or ammo pack.
 - c. Specific products can be offered in limited combinations of shipping medium and lead options.
 - d. Consult product folder for more information on available options.

EXAMPLE BOARD LAYOUT

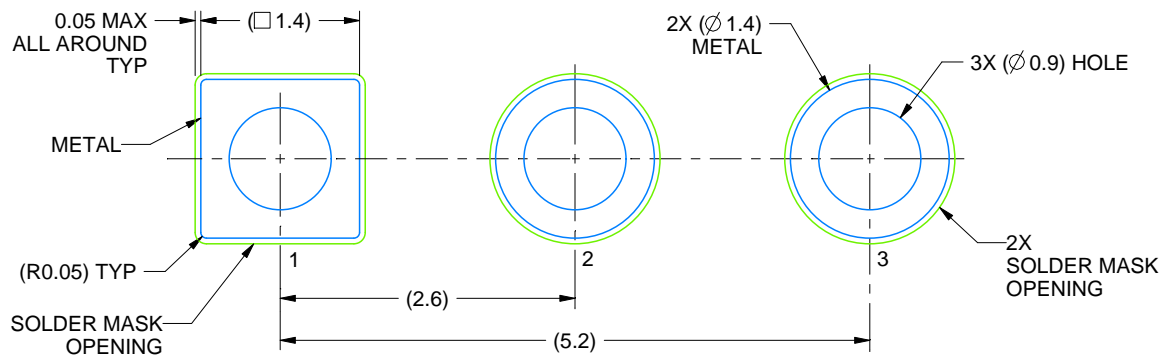
LP0003A

TO-92 - 5.34 mm max height

TO-92



LAND PATTERN EXAMPLE
STRAIGHT LEAD OPTION
NON-SOLDER MASK DEFINED
SCALE:15X



LAND PATTERN EXAMPLE
FORMED LEAD OPTION
NON-SOLDER MASK DEFINED
SCALE:15X

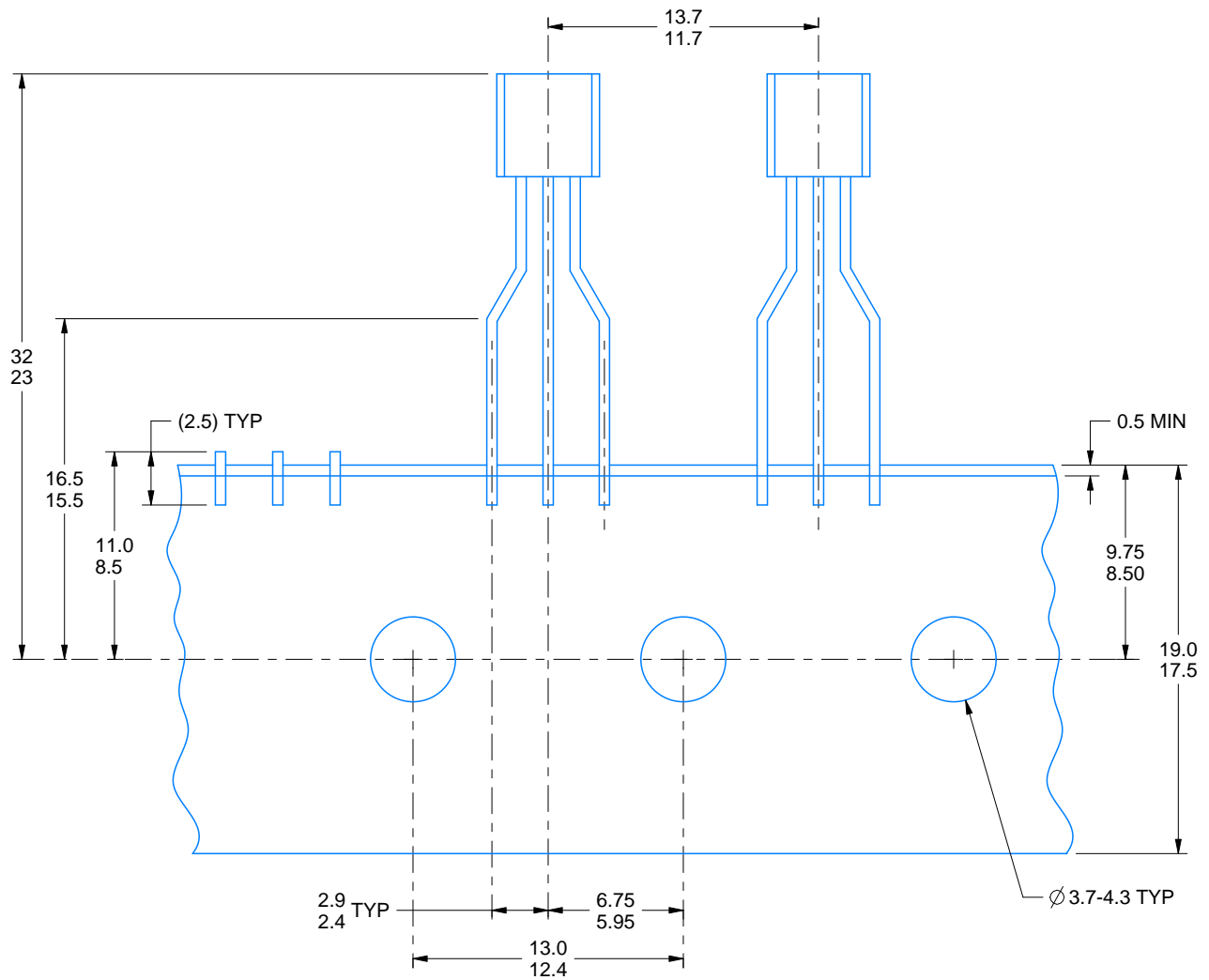
4215214/B 04/2017

TAPE SPECIFICATIONS

LP0003A

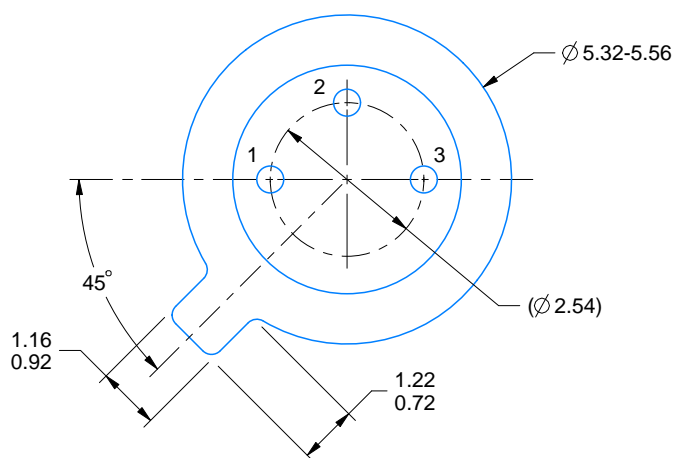
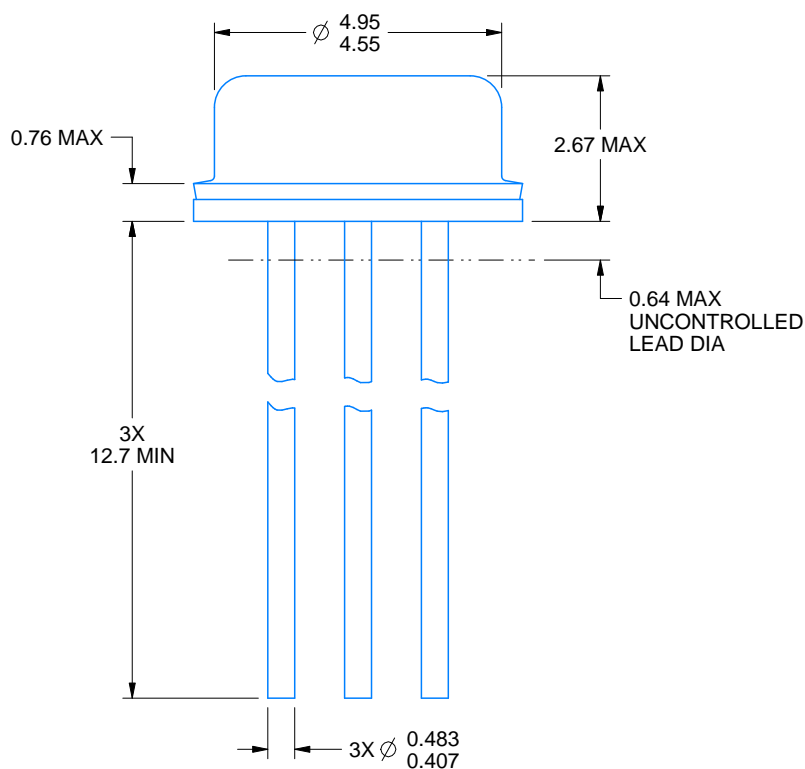
TO-92 - 5.34 mm max height

TO-92



FOR FORMED LEAD OPTION PACKAGE

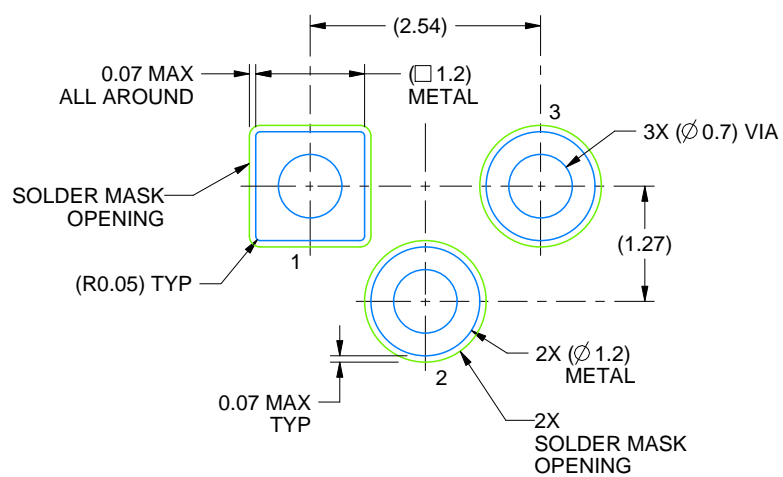
4215214/B 04/2017



4219876/A 01/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration TO-46.



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE:12X



D0008A

PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4214825/C 02/2019

NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

EXAMPLE BOARD LAYOUT

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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